704/705

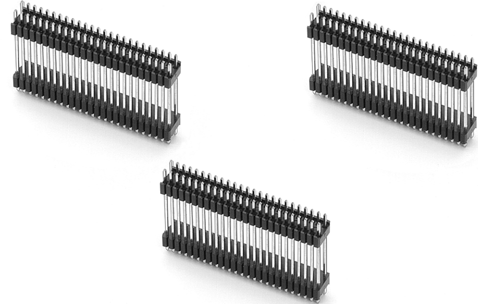
Stiftleisten - 1-/2-reihig - RM 1,27 mm - Sandwich-Version

Pin-Header Strips - Single and Double Row - Pitch 1,27 mm - Dual Body Type

A

Technische Daten / *Technical Data*:

Isolierkörper	Thermoplastischer Kunststoff, nach UL94V0
Insulator	*Thermoplastic, rated UL94V0*
Kontaktmaterial	Stift □ 0,46 mm, CuZn 30
Contact Material	*Pin □ 0,46 mm, CuZn 30*
Kontaktoberfläche	lt. Oberflächenoptionen, über Ni (1,3-2,5 µm)
Contact Surface	*acc. to options (see below), over Ni (1,3-2,5 µm)*
Lötbarkeit	IEC512-12A
Solderability	*IEC512-12A*
Durchgangswiderstand	≤ 20 mOhm
Contact Resistance	*≤ 20 mOhm*
Isolationswiderstand	> $5x10^8$ Ohm
Insulation Resistance	*> $5x10^8$ Ohm*
Spannungsfestigkeit	500 V_{AC}
Test Voltage	*500 V_{AC}*
Nennspannung	250 V_{AC}
Current Voltage	*250 V_{AC}*
Nennstrom	1 A
Current Rating	*1 A*
Temperaturbereich	-40°C...+105°C
Temperature Range	*-40°C...+105°C*
Verarbeitung	Reflow-Lötverfahren; weitere Informationen in Kapitel T
Processing	*Reflow-Soldering, further informations in chapter T*



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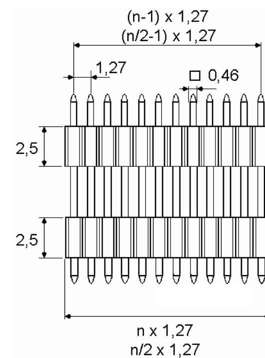
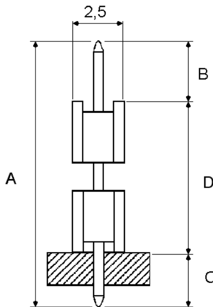
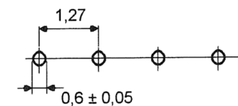


n = Anzahl Kontakte
n = No. of Contacts

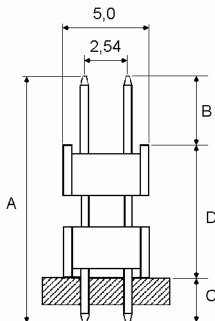
Serie 704



LP-Layout
PCB-Layout

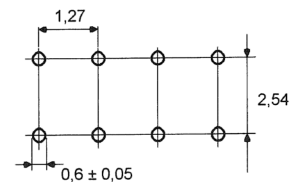


Serie 705

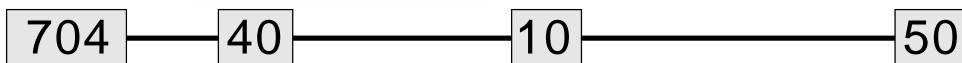


Standard-Maße
Standard-Dimensions

A	B	C
11,0	3,05	3,05



Series* ***Dimensions**** ***Plating****



704 — 40 — 10 — 50

704 = einreihig
single row
705 = zweireihig
double row

002-050-pol. einreihig
single row
004-050-pol. zweireihig
double row

10 = A: 11,0
15 = A: 12,9
20 = A: 15,9
25 = A: 17,9
30 = A: 21,0

Weitere Stiftlängen auf Anfrage
Other Pin Length on Request

10 = 0,25 µm Gold
0,25 µm gold plated
50 = verzinnt
tin plated
60 = sel. Au / Sn
sel. Au / Sn plating

(* Bestellbeispiel - Bitte durch Ihre Spezifikationen ersetzen.
** Order example - To be replaced by your specifications.*)

Reflow-Lötverfahren
Reflow-Soldering

Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflowverfahren verarbeitet werden (Maximalwerte):

Profil Eigenschaft	Bleifreies Löten
Durchschnitts-Ramp-Up Rate (Ts_{max} to Tp)	3 °C / Sek. Max.
Vorheizen - Temperatur Min (Ts_{min}) - Temperatur Max (Ts_{max}) - Zeit (ts_{min} auf ts_{max})	 150°C 200°C 60-180 Sekunden
Verbleiben oberhalb: - Temperatur (T_L) - Zeit (t_L)	 217°C 60-150 Sekunden
Peak/Klassifizierung Temperatur (Tp)	260°C +/- 5°C
Zeit innerhalb von 5°C um die Peak-Temperatur (tp)	20-40 Sekunden
Ramp-Dow n Rate	6°C / Sekunde max.
Zeit von 25°C bis zur Peak-Temperatur	8 Minuten max.

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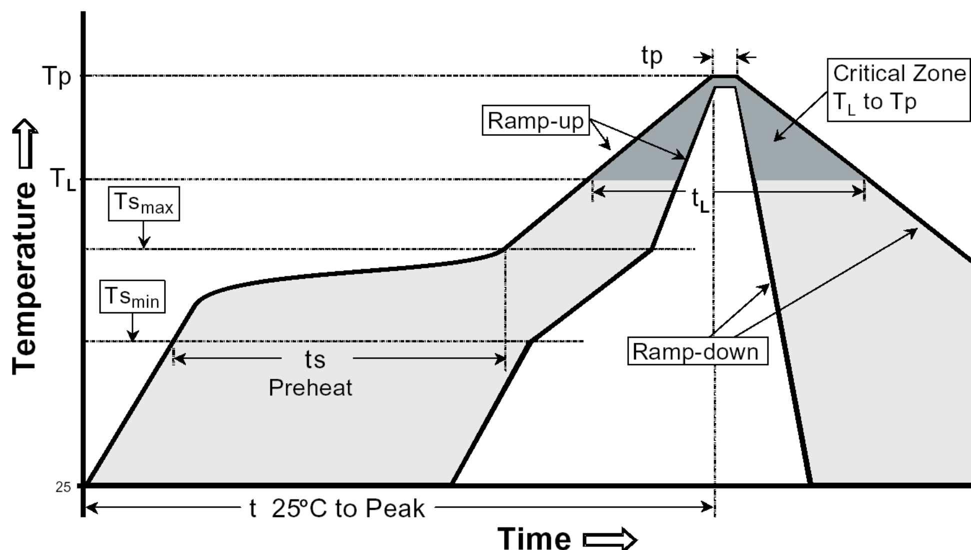
Items should be soldered according to IPC/JEDEC J-STD-020C temperature-profile for leadfree reflow-soldering (maximum values):

Profile Feature	PB-Free assembly
Average Ramp-Up Rate (Ts_{max} to Tp)	3 °C / second max.
Preheat - Temperature Min (Ts_{min}) - Temperature Max (Ts_{max}) - Time (ts_{min} to ts_{max})	 150°C 200°C 60-180 seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	 217°C 60-150 seconds
Peak/Classification Temperature (Tp)	260°C +/- 5°C
Time w ithin 5°C of actual Peak Temperature (tp)	20-40 seconds
Ramp-Dow n Rate	6°C / second max.
Time 25°C to Peak Temperature	8 minutes max.

Empfohlenes Reflow-Lötprofil:
Recommended Reflow-Soldering profile:



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